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ABSTRACT OF THE DISCLOSURE

A semiconductor device comprises a substantially flat interconnection substrate having an interconnection pattern formed on a surface thereof. A semiconductor element is mounted on the substantially flat interconnection substrate so that an electrode terminal of the semiconductor element is electrically connected to the interconnection pattern. A heat radiation plate is formed in a form of a sheet having a concave portion so as to cover the semiconductor element and is bonded on the surface of the substantially flat interconnection substrate. An external connection terminal is formed on the other surface of the substantially flat interconnection substrate so as to penetrate through the substantially flat interconnection substrate and be electrically connected to the interconnection pattern. The heat radiation plate is formed of a heat-resistant resin containing carbon fibers.